



N-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$r_{DS(on)}(\Omega)$	I _D (A)		
20	0.065 @ V _{GS} = 4.5 V	3.9		
	0.075 @ V _{GS} = 2.5 V	3.6		
	0.096 @ V _{GS} = 1.8 V	3.2		

FEATURES

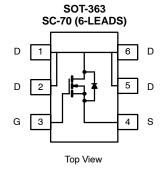
- TrenchFET® Power MOSFETS
- 1.8-V Rated
- Thermally Enhanced SC-70 Package

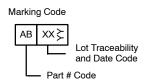


Pb-free Available

APPLICATIONS

- Load Switching
- PA Switch
- Level Switch





Ordering Information: Si1406DH-T1

Si1406DH-T1—E3 (Lead (Pb)-Free)

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C UNLESS OTHERWISE NOTED)						
Parameter		Symbol	5 secs	Steady State	Unit	
Drain-Source Voltage		V _{DS}	20		V	
Gate-Source Voltage		V _{GS}	±8			
Continuous Drain Current (T, I = 150°C)a	T _A = 25°C	I _D	3.9	3.1	A	
Continuous Brain Guiterit (1) = 130 O)	T _A = 85°C		2.8	2.2		
Pulsed Drain Current		I _{DM}	10		^	
Continuous Diode Current (Diode Conduction) ^a		I _S	1.4	0.9		
Martinuar Davis Discipations	T _A = 25°C	P _D	1.56	1.0	w	
Maximum Power Dissipation ^a	T _A = 85°C		0.81	0.52		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to 150		°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
	t ≤ 5 sec	R _{thJA}	60	80	°C/W
Maximum Junction-to-Ambient ^a	Steady State		100	125	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	34	45	

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

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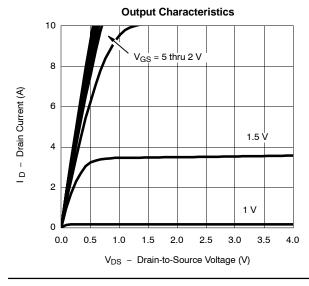
SPECIFICATIONS (T _J = 25°C UNLESS OTHERWISE NOTED)								
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit		
Static								
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	0.45		1.2	٧		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{LI} = 85^{\circ}\text{C}$			1 5	μΑ		
On-State Drain Current ^a	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 4.5 V	8		"	Α		
		$V_{GS} = 4.5 \text{ V}, I_D = 3.9 \text{ A}$		0.053	0.065			
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = 2.5 V, I _D = 3.6 A		0.062	0.075	Ω		
		$V_{GS} = 1.8 \text{ V}, I_D = 2 \text{ A}$		0.079	0.096			
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 10 \text{ V}, I_D = 3.9 \text{ A}$		11		S		
Diode Forward Voltage ^a	V _{SD}	$I_S = 1.4 \text{ A}, V_{GS} = 0 \text{ V}$		0.75	1.1	V		
Dynamic ^b			•	1	•	•		
Total Gate Charge	Qg			4.9	7.5	nC		
Gate-Source Charge	Q _{gs}	$V_{DS} = 10 \text{ V}, \ V_{GS} = 4.5 \text{ V}, \ I_D = 3.9 \text{ A}$		1.0				
Gate-Drain Charge	Q _{gd}			0.95				
Turn-On Delay Time	t _{d(on)}			27	41			
Rise Time	t _r	$V_{DD} = 10 \text{ V, R}_{1} = 20 \Omega$		47	71	ns		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 0.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 6 \Omega$		54	81			
Fall Time	t _f			29	44			
Source-Drain Reverse Recovery	t _{rr}	I _F = 1.4 A. di/dt = 100/μs		35	60	1		

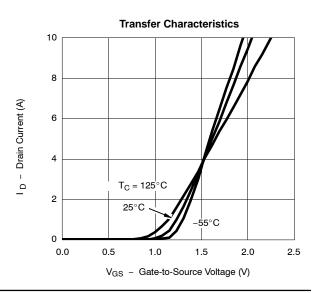
Notes

- Pulse test; pulse width $\leq 300~\mu s$, duty cycle $\leq 2\%$. Guaranteed by design, not subject to production testing. b.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)



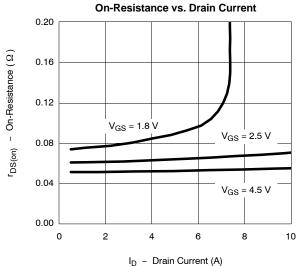




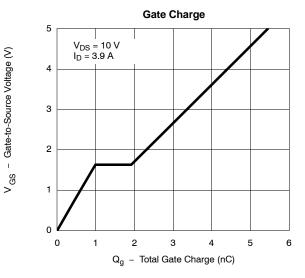




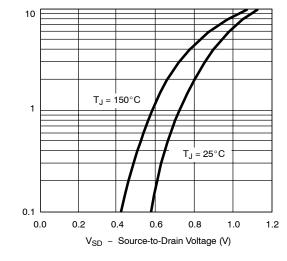
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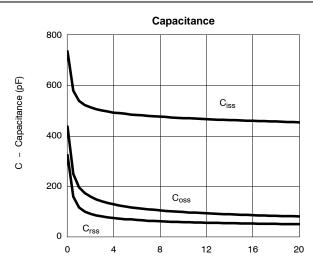






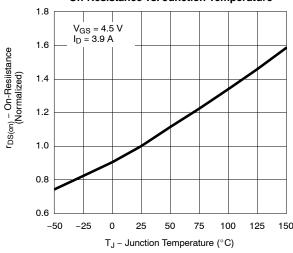
Source-Drain Diode Forward Voltage



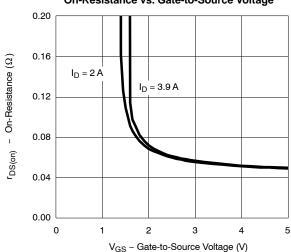


V_{DS} - Drain-to-Source Voltage (V)

On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-to-Source Voltage

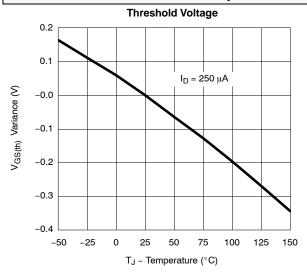


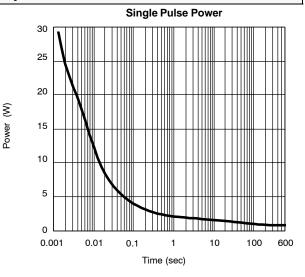
Source Current (A)

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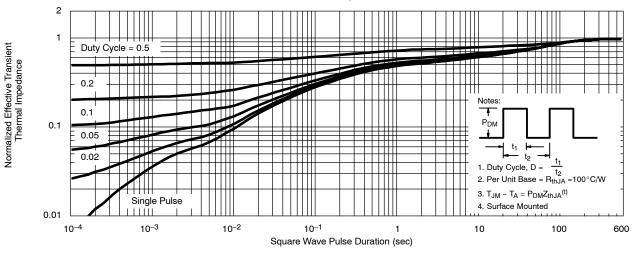


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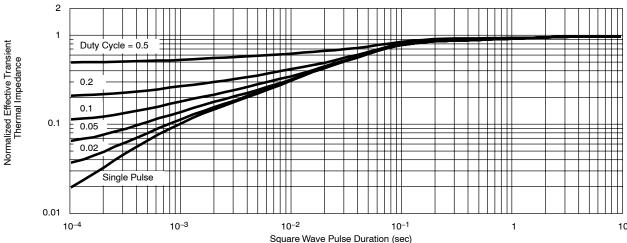




Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



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